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### Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

#### Details

Product Status	Obsolete
Number of LABs/CLBs	158500
Number of Logic Elements/Cells	420000
Total RAM Bits	37888000
Number of I/O	600
Number of Gates	-
Voltage - Supply	0.82V ~ 0.88V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1152-BBGA, FCBGA
Supplier Device Package	1152-FBGA (35x35)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/intel/5sgxma4k3f35i4n">https://www.e-xfl.com/product-detail/intel/5sgxma4k3f35i4n</a>

## Recommended Operating Conditions

This section lists the functional operating limits for the AC and DC parameters for Stratix V devices. Table 6 lists the steady-state voltage and current values expected from Stratix V devices. Power supply ramps must all be strictly monotonic, without plateaus.

**Table 6. Recommended Operating Conditions for Stratix V Devices (Part 1 of 2)**

Symbol	Description	Condition	Min <sup>(4)</sup>	Typ	Max <sup>(4)</sup>	Unit
V <sub>CC</sub>	Core voltage and periphery circuitry power supply (C1, C2, I2, and I3YY speed grades)	—	0.87	0.9	0.93	V
	Core voltage and periphery circuitry power supply (C2L, C3, C4, I2L, I3, I3L, and I4 speed grades) <sup>(3)</sup>	—	0.82	0.85	0.88	V
V <sub>CCPT</sub>	Power supply for programmable power technology	—	1.45	1.50	1.55	V
V <sub>CC_AUX</sub>	Auxiliary supply for the programmable power technology	—	2.375	2.5	2.625	V
V <sub>CCPD</sub> <sup>(1)</sup>	I/O pre-driver (3.0 V) power supply	—	2.85	3.0	3.15	V
	I/O pre-driver (2.5 V) power supply	—	2.375	2.5	2.625	V
V <sub>CCIO</sub>	I/O buffers (3.0 V) power supply	—	2.85	3.0	3.15	V
	I/O buffers (2.5 V) power supply	—	2.375	2.5	2.625	V
	I/O buffers (1.8 V) power supply	—	1.71	1.8	1.89	V
	I/O buffers (1.5 V) power supply	—	1.425	1.5	1.575	V
	I/O buffers (1.35 V) power supply	—	1.283	1.35	1.45	V
	I/O buffers (1.25 V) power supply	—	1.19	1.25	1.31	V
	I/O buffers (1.2 V) power supply	—	1.14	1.2	1.26	V
V <sub>CCPGM</sub>	Configuration pins (3.0 V) power supply	—	2.85	3.0	3.15	V
	Configuration pins (2.5 V) power supply	—	2.375	2.5	2.625	V
	Configuration pins (1.8 V) power supply	—	1.71	1.8	1.89	V
V <sub>CCA_FPLL</sub>	PLL analog voltage regulator power supply	—	2.375	2.5	2.625	V
V <sub>CCD_FPLL</sub>	PLL digital voltage regulator power supply	—	1.45	1.5	1.55	V
V <sub>CCBAT</sub> <sup>(2)</sup>	Battery back-up power supply (For design security volatile key register)	—	1.2	—	3.0	V
V <sub>I</sub>	DC input voltage	—	−0.5	—	3.6	V
V <sub>O</sub>	Output voltage	—	0	—	V <sub>CCIO</sub>	V
T <sub>J</sub>	Operating junction temperature	Commercial	0	—	85	°C
		Industrial	−40	—	100	°C

Table 8 shows the transceiver power supply voltage requirements for various conditions.

**Table 8. Transceiver Power Supply Voltage Requirements**

Conditions	Core Speed Grade	VCCR_GXB & VCCT_GXB <sup>(2)</sup>	VCCA_GXB	VCCH_GXB	Unit
If BOTH of the following conditions are true: <ul style="list-style-type: none"> <li>■ Data rate &gt; 10.3 Gbps.</li> <li>■ DFE is used.</li> </ul>	All	1.05	3.0	1.5	V
If ANY of the following conditions are true <sup>(1)</sup> : <ul style="list-style-type: none"> <li>■ ATX PLL is used.</li> <li>■ Data rate &gt; 6.5Gbps.</li> <li>■ DFE (data rate ≤ 10.3 Gbps), AEQ, or EyeQ feature is used.</li> </ul>	All	1.0			
If ALL of the following conditions are true: <ul style="list-style-type: none"> <li>■ ATX PLL is not used.</li> <li>■ Data rate ≤ 6.5Gbps.</li> <li>■ DFE, AEQ, and EyeQ are not used.</li> </ul>	C1, C2, I2, and I3YY	0.90	2.5		
	C2L, C3, C4, I2L, I3, I3L, and I4	0.85	2.5		

**Notes to Table 8:**

- (1) Choose this power supply voltage requirement option if you plan to upgrade your design later with any of the listed conditions.
- (2) If the VCCR\_GXB and VCCT\_GXB supplies are set to 1.0 V or 1.05 V, they cannot be shared with the VCC core supply. If the VCCR\_GXB and VCCT\_GXB are set to either 0.90 V or 0.85 V, they can be shared with the VCC core supply.

## DC Characteristics

This section lists the supply current, I/O pin leakage current, input pin capacitance, on-chip termination tolerance, and hot socketing specifications.

### Supply Current

Supply current is the current drawn from the respective power rails used for power budgeting. Use the Excel-based Early Power Estimator (EPE) to get supply current estimates for your design because these currents vary greatly with the resources you use.



For more information about power estimation tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter in the *Quartus II Handbook*.

**Table 11. OCT Calibration Accuracy Specifications for Stratix V Devices <sup>(1)</sup> (Part 2 of 2)**

Symbol	Description	Conditions	Calibration Accuracy				Unit
			C1	C2,I2	C3,I3,I3YY	C4,I4	
50-Ω R <sub>S</sub>	Internal series termination with calibration (50-Ω setting)	V <sub>CCIO</sub> = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	±15	±15	%
34-Ω and 40-Ω R <sub>S</sub>	Internal series termination with calibration (34-Ω and 40-Ω setting)	V <sub>CCIO</sub> = 1.5, 1.35, 1.25, 1.2 V	±15	±15	±15	±15	%
48-Ω, 60-Ω, 80-Ω, and 240-Ω R <sub>S</sub>	Internal series termination with calibration (48-Ω, 60-Ω, 80-Ω, and 240-Ω setting)	V <sub>CCIO</sub> = 1.2 V	±15	±15	±15	±15	%
50-Ω R <sub>T</sub>	Internal parallel termination with calibration (50-Ω setting)	V <sub>CCIO</sub> = 2.5, 1.8, 1.5, 1.2 V	-10 to +40	-10 to +40	-10 to +40	-10 to +40	%
20-Ω, 30-Ω, 40-Ω, 60-Ω, and 120-Ω R <sub>T</sub>	Internal parallel termination with calibration (20-Ω, 30-Ω, 40-Ω, 60-Ω, and 120-Ω setting)	V <sub>CCIO</sub> = 1.5, 1.35, 1.25 V	-10 to +40	-10 to +40	-10 to +40	-10 to +40	%
60-Ω and 120-Ω R <sub>T</sub>	Internal parallel termination with calibration (60-Ω and 120-Ω setting)	V <sub>CCIO</sub> = 1.2	-10 to +40	-10 to +40	-10 to +40	-10 to +40	%
25-Ω R <sub>S_left_shift</sub>	Internal left shift series termination with calibration (25-Ω R <sub>S_left_shift</sub> setting)	V <sub>CCIO</sub> = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	±15	±15	%

**Note to Table 11:**

(1) OCT calibration accuracy is valid at the time of calibration only.

Table 12 lists the Stratix V OCT without calibration resistance tolerance to PVT changes.

**Table 12. OCT Without Calibration Resistance Tolerance Specifications for Stratix V Devices (Part 1 of 2)**

Symbol	Description	Conditions	Resistance Tolerance				Unit
			C1	C2,I2	C3, I3, I3YY	C4, I4	
25-Ω R, 50-Ω R <sub>S</sub>	Internal series termination without calibration (25-Ω setting)	V <sub>CCIO</sub> = 3.0 and 2.5 V	±30	±30	±40	±40	%
25-Ω R <sub>S</sub>	Internal series termination without calibration (25-Ω setting)	V <sub>CCIO</sub> = 1.8 and 1.5 V	±30	±30	±40	±40	%
25-Ω R <sub>S</sub>	Internal series termination without calibration (25-Ω setting)	V <sub>CCIO</sub> = 1.2 V	±35	±35	±50	±50	%

-  You typically use the interactive Excel-based Early Power Estimator before designing the FPGA to get a magnitude estimate of the device power. The Quartus II PowerPlay Power Analyzer provides better quality estimates based on the specifics of the design after you complete place-and-route. The PowerPlay Power Analyzer can apply a combination of user-entered, simulation-derived, and estimated signal activities that, when combined with detailed circuit models, yields very accurate power estimates.
-  For more information about power estimation tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter in the *Quartus II Handbook*.

## Switching Characteristics

This section provides performance characteristics of the Stratix V core and periphery blocks.

These characteristics can be designated as Preliminary or Final.

- Preliminary characteristics are created using simulation results, process data, and other known parameters. The title of these tables show the designation as “Preliminary.”
- Final numbers are based on actual silicon characterization and testing. The numbers reflect the actual performance of the device under worst-case silicon process, voltage, and junction temperature conditions. There are no designations on finalized tables.

### Transceiver Performance Specifications

This section describes transceiver performance specifications.

Table 23 lists the Stratix V GX and GS transceiver specifications.

**Table 23. Transceiver Specifications for Stratix V GX and GS Devices <sup>(1)</sup> (Part 1 of 7)**

Symbol/ Description	Conditions	Transceiver Speed Grade 1			Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Reference Clock											
Supported I/O Standards	Dedicated reference clock pin	1.2-V PCML, 1.4-V PCML, 1.5-V PCML, 2.5-V PCML, Differential LVPECL, LVDS, and HCSL									
	RX reference clock pin	1.4-V PCML, 1.5-V PCML, 2.5-V PCML, LVPECL, and LVDS									
Input Reference Clock Frequency (CMU PLL) <sup>(8)</sup>	—	40	—	710	40	—	710	40	—	710	MHz
Input Reference Clock Frequency (ATX PLL) <sup>(8)</sup>	—	100	—	710	100	—	710	100	—	710	MHz
Rise time	Measure at ±60 mV of differential signal <sup>(26)</sup>	—	—	400	—	—	400	—	—	400	ps
Fall time	Measure at ±60 mV of differential signal <sup>(26)</sup>	—	—	400	—	—	400	—	—	400	
Duty cycle	—	45	—	55	45	—	55	45	—	55	%
Spread-spectrum modulating clock frequency	PCI Express® (PCIe®)	30	—	33	30	—	33	30	—	33	kHz

**Table 23. Transceiver Specifications for Stratix V GX and GS Devices <sup>(1)</sup> (Part 4 of 7)**

Symbol/ Description	Conditions	Transceiver Speed Grade 1			Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Differential on-chip termination resistors <sup>(21)</sup>	85- $\Omega$ setting	—	85 $\pm$ 30%	—	—	85 $\pm$ 30%	—	—	85 $\pm$ 30%	—	$\Omega$
	100- $\Omega$ setting	—	100 $\pm$ 30%	—	—	100 $\pm$ 30%	—	—	100 $\pm$ 30%	—	$\Omega$
	120- $\Omega$ setting	—	120 $\pm$ 30%	—	—	120 $\pm$ 30%	—	—	120 $\pm$ 30%	—	$\Omega$
	150- $\Omega$ setting	—	150 $\pm$ 30%	—	—	150 $\pm$ 30%	—	—	150 $\pm$ 30%	—	$\Omega$
$V_{ICM}$ (AC and DC coupled)	$V_{CCR\_GXB} = 0.85\text{ V}$ or 0.9 V full bandwidth	—	600	—	—	600	—	—	600	—	mV
	$V_{CCR\_GXB} = 0.85\text{ V}$ or 0.9 V half bandwidth	—	600	—	—	600	—	—	600	—	mV
	$V_{CCR\_GXB} = 1.0\text{ V}/1.05\text{ V}$ full bandwidth	—	700	—	—	700	—	—	700	—	mV
	$V_{CCR\_GXB} = 1.0\text{ V}$ half bandwidth	—	750	—	—	750	—	—	750	—	mV
$t_{LTR}$ <sup>(11)</sup>	—	—	—	10	—	—	10	—	—	10	$\mu\text{s}$
$t_{LTD}$ <sup>(12)</sup>	—	4	—	—	4	—	—	4	—	—	$\mu\text{s}$
$t_{LTD\_manual}$ <sup>(13)</sup>	—	4	—	—	4	—	—	4	—	—	$\mu\text{s}$
$t_{LTR\_LTD\_manual}$ <sup>(14)</sup>	—	15	—	—	15	—	—	15	—	—	$\mu\text{s}$
Run Length	—	—	—	200	—	—	200	—	—	200	UI
Programmable equalization (AC Gain) <sup>(10)</sup>	Full bandwidth (6.25 GHz) Half bandwidth (3.125 GHz)	—	—	16	—	—	16	—	—	16	dB

Table 27 shows the  $V_{OD}$  settings for the GX channel.

**Table 27. Typical  $V_{OD}$  Setting for GX Channel, TX Termination = 100  $\Omega$  <sup>(2)</sup>**

Symbol	$V_{OD}$ Setting	$V_{OD}$ Value (mV)	$V_{OD}$ Setting	$V_{OD}$ Value (mV)
<b><math>V_{OD}</math> differential peak to peak typical <sup>(3)</sup></b>	0 <sup>(1)</sup>	0	32	640
	1 <sup>(1)</sup>	20	33	660
	2 <sup>(1)</sup>	40	34	680
	3 <sup>(1)</sup>	60	35	700
	4 <sup>(1)</sup>	80	36	720
	5 <sup>(1)</sup>	100	37	740
	6	120	38	760
	7	140	39	780
	8	160	40	800
	9	180	41	820
	10	200	42	840
	11	220	43	860
	12	240	44	880
	13	260	45	900
	14	280	46	920
	15	300	47	940
	16	320	48	960
	17	340	49	980
	18	360	50	1000
	19	380	51	1020
	20	400	52	1040
	21	420	53	1060
	22	440	54	1080
	23	460	55	1100
	24	480	56	1120
	25	500	57	1140
	26	520	58	1160
	27	540	59	1180
	28	560	60	1200
	29	580	61	1220
	30	600	62	1240
	31	620	63	1260

**Note to Table 27:**

- (1) If TX termination resistance = 100 $\Omega$ , this VOD setting is illegal.
- (2) The tolerance is +/-20% for all VOD settings except for settings 2 and below.
- (3) Refer to Figure 2.



**Table 28. Transceiver Specifications for Stratix V GT Devices (Part 3 of 5) <sup>(1)</sup>**

Symbol/ Description	Conditions	Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	
Differential on-chip termination resistors <sup>(7)</sup>	GT channels	—	100	—	—	100	—	$\Omega$
Differential on-chip termination resistors for GX channels <sup>(19)</sup>	85- $\Omega$ setting	—	85 $\pm$ 30%	—	—	85 $\pm$ 30%	—	$\Omega$
	100- $\Omega$ setting	—	100 $\pm$ 30%	—	—	100 $\pm$ 30%	—	$\Omega$
	120- $\Omega$ setting	—	120 $\pm$ 30%	—	—	120 $\pm$ 30%	—	$\Omega$
	150- $\Omega$ setting	—	150 $\pm$ 30%	—	—	150 $\pm$ 30%	—	$\Omega$
V <sub>ICM</sub> (AC coupled)	GT channels	—	650	—	—	650	—	mV
VICM (AC and DC coupled) for GX Channels	VCCR_GXB = 0.85 V or 0.9 V	—	600	—	—	600	—	mV
	VCCR_GXB = 1.0 V full bandwidth	—	700	—	—	700	—	mV
	VCCR_GXB = 1.0 V half bandwidth	—	750	—	—	750	—	mV
t <sub>LTR</sub> <sup>(9)</sup>	—	—	—	10	—	—	10	$\mu$ s
t <sub>LTD</sub> <sup>(10)</sup>	—	4	—	—	4	—	—	$\mu$ s
t <sub>LTD_manual</sub> <sup>(11)</sup>	—	4	—	—	4	—	—	$\mu$ s
t <sub>LTR_LTD_manual</sub> <sup>(12)</sup>	—	15	—	—	15	—	—	$\mu$ s
Run Length	GT channels	—	—	72	—	—	72	CID
	GX channels	<sup>(8)</sup>						
CDR PPM	GT channels	—	—	1000	—	—	1000	$\pm$ PPM
	GX channels	<sup>(8)</sup>						
Programmable equalization (AC Gain) <sup>(5)</sup>	GT channels	—	—	14	—	—	14	dB
	GX channels	<sup>(8)</sup>						
Programmable DC gain <sup>(6)</sup>	GT channels	—	—	7.5	—	—	7.5	dB
	GX channels	<sup>(8)</sup>						
Differential on-chip termination resistors <sup>(7)</sup>	GT channels	—	100	—	—	100	—	$\Omega$
<b>Transmitter</b>								
Supported I/O Standards	—	1.4-V and 1.5-V PCML						
Data rate (Standard PCS)	GX channels	600	—	8500	600	—	8500	Mbps
Data rate (10G PCS)	GX channels	600	—	12,500	600	—	12,500	Mbps

**Table 28. Transceiver Specifications for Stratix V GT Devices (Part 4 of 5) <sup>(1)</sup>**

Symbol/ Description	Conditions	Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	
Data rate	GT channels	19,600	—	28,050	19,600	—	25,780	Mbps
Differential on-chip termination resistors	GT channels	—	100	—	—	100	—	Ω
	GX channels	(8)						
V <sub>OCM</sub> (AC coupled)	GT channels	—	500	—	—	500	—	mV
	GX channels	(8)						
Rise/Fall time	GT channels	—	15	—	—	15	—	ps
	GX channels	(8)						
Intra-differential pair skew	GX channels	(8)						
Intra-transceiver block transmitter channel-to- channel skew	GX channels	(8)						
Inter-transceiver block transmitter channel-to- channel skew	GX channels	(8)						
CMU PLL								
Supported Data Range	—	600	—	12500	600	—	8500	Mbps
t <sub>pll_powerdown</sub> <sup>(13)</sup>	—	1	—	—	1	—	—	μs
t <sub>pll_lock</sub> <sup>(14)</sup>	—	—	—	10	—	—	10	μs
ATX PLL								
Supported Data Rate Range for GX Channels	VCO post- divider L=2	8000	—	12500	8000	—	8500	Mbps
	L=4	4000	—	6600	4000	—	6600	Mbps
	L=8	2000	—	3300	2000	—	3300	Mbps
	L=8, Local/Central Clock Divider =2	1000	—	1762.5	1000	—	1762.5	Mbps
Supported Data Rate Range for GT Channels	VCO post- divider L=2	9800	—	14025	9800	—	12890	Mbps
t <sub>pll_powerdown</sub> <sup>(13)</sup>	—	1	—	—	1	—	—	μs
t <sub>pll_lock</sub> <sup>(14)</sup>	—	—	—	10	—	—	10	μs
fPLL								
Supported Data Range	—	600	—	3250/ 3.125 <sup>(23)</sup>	600	—	3250/ 3.125 <sup>(23)</sup>	Mbps
t <sub>pll_powerdown</sub> <sup>(13)</sup>	—	1	—	—	1	—	—	μs

Figure 4 shows the differential transmitter output waveform.

**Figure 4. Differential Transmitter/Receiver Output/Input Waveform**



Figure 5 shows the Stratix V AC gain curves for GT channels.

**Figure 5. AC Gain Curves for GT Channels**

- XFI
- ASI
- HiGig/HiGig+
- HiGig2/HiGig2+
- Serial Data Converter (SDC)
- GPON
- SDI
- SONET
- Fibre Channel (FC)
- PCIe
- QPI
- SFF-8431

Download the Stratix V Characterization Report Tool to view the characterization report summary for these protocols.

## Core Performance Specifications

This section describes the clock tree, phase-locked loop (PLL), digital signal processing (DSP), memory blocks, configuration, and JTAG specifications.

### Clock Tree Specifications

Table 30 lists the clock tree specifications for Stratix V devices.

**Table 30. Clock Tree Performance for Stratix V Devices <sup>(1)</sup>**

Symbol	Performance			Unit
	C1, C2, C2L, I2, and I2L	C3, I3, I3L, and I3YY	C4, I4	
Global and Regional Clock	717	650	580	MHz
Periphery Clock	550	500	500	MHz

**Note to Table 30:**

(1) The Stratix V ES devices are limited to 600 MHz core clock tree performance.

**Table 36. High-Speed I/O Specifications for Stratix V Devices <sup>(1), (2)</sup> (Part 4 of 4)**

Symbol	Conditions	C1			C2, C2L, I2, I2L			C3, I3, I3L, I3YY			C4, I4			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
f <sub>HSDR</sub> (data rate)	SERDES factor J = 3 to 10	(6)	—	(8)	(6)	—	(8)	(6)	—	(8)	(6)	—	(8)	Mbps
	SERDES factor J = 2, uses DDR Registers	(6)	—	(7)	(6)	—	(7)	(6)	—	(7)	(6)	—	(7)	Mbps
	SERDES factor J = 1, uses SDR Register	(6)	—	(7)	(6)	—	(7)	(6)	—	(7)	(6)	—	(7)	Mbps
<b>DPA Mode</b>														
DPA run length	—	—	—	1000 0	—	—	1000 0	—	—	1000 0	—	—	1000 0	UI
<b>Soft CDR mode</b>														
Soft-CDR PPM tolerance	—	—	—	300	—	—	300	—	—	300	—	—	300	± PPM
<b>Non DPA Mode</b>														
Sampling Window	—	—	—	300	—	—	300	—	—	300	—	—	300	ps

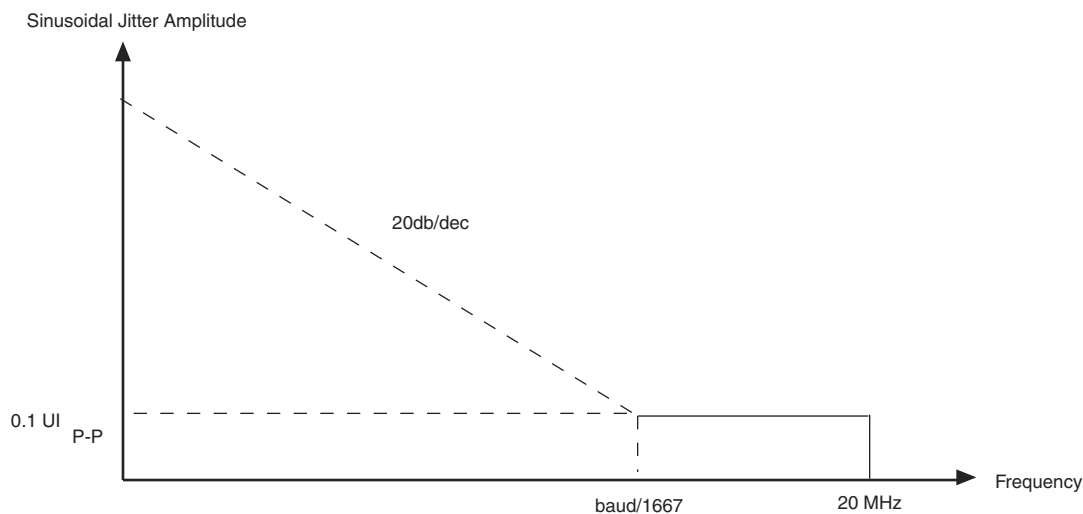
**Notes to Table 36:**

- (1) When J = 3 to 10, use the serializer/deserializer (SERDES) block.
- (2) When J = 1 or 2, bypass the SERDES block.
- (3) This only applies to DPA and soft-CDR modes.
- (4) Clock Boost Factor (W) is the ratio between the input data rate to the input clock rate.
- (5) This is achieved by using the **LVDS** clock network.
- (6) The minimum specification depends on the clock source (for example, the PLL and clock pin) and the clock routing resource (global, regional, or local) that you use. The I/O differential buffer and input register do not have a minimum toggle rate.
- (7) The maximum ideal frequency is the SERDES factor (J) x the PLL maximum output frequency (f<sub>OUT</sub>) provided you can close the design timing and the signal integrity simulation is clean.
- (8) You can estimate the achievable maximum data rate for non-DPA mode by performing link timing closure analysis. You must consider the board skew margin, transmitter delay margin, and receiver sampling margin to determine the maximum data rate supported.
- (9) If the receiver with DPA enabled and transmitter are using shared PLLs, the minimum data rate is 150 Mbps.
- (10) You must calculate the leftover timing margin in the receiver by performing link timing closure analysis. You must consider the board skew margin, transmitter channel-to-channel skew, and receiver sampling margin to determine leftover timing margin.
- (11) The F<sub>MAX</sub> specification is based on the fast clock used for serial data. The interface F<sub>MAX</sub> is also dependent on the parallel clock domain which is design-dependent and requires timing analysis.
- (12) Stratix V RX LVDS will need DPA. For Stratix V TX LVDS, the receiver side component must have DPA.
- (13) Stratix V LVDS serialization and de-serialization factor needs to be x4 and above.
- (14) Requires package skew compensation with PCB trace length.
- (15) Do not mix single-ended I/O buffer within LVDS I/O bank.
- (16) Chip-to-chip communication only with a maximum load of 5 pF.
- (17) When using True LVDS RX channels for emulated LVDS TX channel, only serialization factors 1 and 2 are supported.

**Table 38. LVDS Soft-CDR/DPA Sinusoidal Jitter Mask Values for a Data Rate  $\geq 1.25$  Gbps**

Jitter Frequency (Hz)		Sinusoidal Jitter (UI)
F1	10,000	25.000
F2	17,565	25.000
F3	1,493,000	0.350
F4	50,000,000	0.350

Figure 9 shows the LVDS soft-CDR/DPA sinusoidal jitter tolerance specification for a data rate  $< 1.25$  Gbps.

**Figure 9. LVDS Soft-CDR/DPA Sinusoidal Jitter Tolerance Specification for a Data Rate  $< 1.25$  Gbps**

### DLL Range, DQS Logic Block, and Memory Output Clock Jitter Specifications

Table 39 lists the DLL range specification for Stratix V devices. The DLL is always in 8-tap mode in Stratix V devices.

**Table 39. DLL Range Specifications for Stratix V Devices <sup>(1)</sup>**

C1	C2, C2L, I2, I2L	C3, I3, I3L, I3YY	C4,I4	Unit
300-933	300-933	300-890	300-890	MHz

**Note to Table 39:**

- (1) Stratix V devices support memory interface frequencies lower than 300 MHz, although the reference clock that feeds the DLL must be at least 300 MHz. To support interfaces below 300 MHz, multiply the reference clock feeding the DLL to ensure the frequency is within the supported range of the DLL.

Table 40 lists the DQS phase offset delay per stage for Stratix V devices.

**Table 40. DQS Phase Offset Delay Per Setting for Stratix V Devices <sup>(1), (2)</sup> (Part 1 of 2)**

Speed Grade	Min	Max	Unit
C1	8	14	ps
C2, C2L, I2, I2L	8	14	ps
C3,I3, I3L, I3YY	8	15	ps

**Table 42. Memory Output Clock Jitter Specification for Stratix V Devices <sup>(1)</sup>, (Part 2 of 2) <sup>(2)</sup>, <sup>(3)</sup>**

Clock Network	Parameter	Symbol	C1		C2, C2L, I2, I2L		C3, I3, I3L, I3YY		C4,I4		Unit
			Min	Max	Min	Max	Min	Max	Min	Max	
PHY Clock	Clock period jitter	$t_{JIT(per)}$	-25	25	-25	25	-30	30	-35	35	ps
	Cycle-to-cycle period jitter	$t_{JIT(cc)}$	-50	50	-50	50	-60	60	-70	70	ps
	Duty cycle jitter	$t_{JIT(duty)}$	-37.5	37.5	-37.5	37.5	-45	45	-56	56	ps

**Notes to Table 42:**

- (1) The clock jitter specification applies to the memory output clock pins generated using differential signal-splitter and DDIO circuits clocked by a PLL output routed on a PHY, regional, or global clock network as specified. Altera recommends using PHY clock networks whenever possible.
- (2) The clock jitter specification applies to the memory output clock pins clocked by an integer PLL.
- (3) The memory output clock jitter is applicable when an input jitter of 30 ps peak-to-peak is applied with bit error rate (BER) -12, equivalent to 14 sigma.

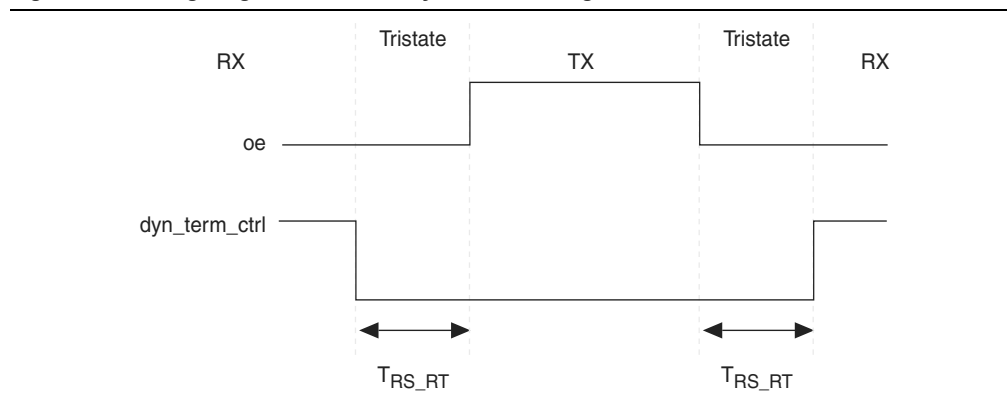
**OCT Calibration Block Specifications**

Table 43 lists the OCT calibration block specifications for Stratix V devices.

**Table 43. OCT Calibration Block Specifications for Stratix V Devices**

Symbol	Description	Min	Typ	Max	Unit
OCTUSRCLK	Clock required by the OCT calibration blocks	—	—	20	MHz
$T_{OCTCAL}$	Number of OCTUSRCLK clock cycles required for OCT $R_S/R_T$ calibration	—	1000	—	Cycles
$T_{OCTSHIFT}$	Number of OCTUSRCLK clock cycles required for the OCT code to shift out	—	32	—	Cycles
$T_{RS\_RT}$	Time required between the <code>dyn_term_ctrl</code> and <code>oe</code> signal transitions in a bidirectional I/O buffer to dynamically switch between OCT $R_S$ and $R_T$ (Figure 10)	—	2.5	—	ns

Figure 10 shows the timing diagram for the `oe` and `dyn_term_ctrl` signals.

**Figure 10. Timing Diagram for `oe` and `dyn_term_ctrl` Signals**

**Table 48. Minimum Configuration Time Estimation for Stratix V Devices**

Variant	Member Code	Active Serial <sup>(1)</sup>			Fast Passive Parallel <sup>(2)</sup>		
		Width	DCLK (MHz)	Min Config Time (s)	Width	DCLK (MHz)	Min Config Time (s)
GS	D3	4	100	0.344	32	100	0.043
	D4	4	100	0.534	32	100	0.067
		4	100	0.344	32	100	0.043
	D5	4	100	0.534	32	100	0.067
	D6	4	100	0.741	32	100	0.093
	D8	4	100	0.741	32	100	0.093
E	E9	4	100	0.857	32	100	0.107
	EB	4	100	0.857	32	100	0.107

**Notes to Table 48:**

- (1) DCLK frequency of 100 MHz using external CLKUSR.  
 (2) Max FPGA FPP bandwidth may exceed bandwidth available from some external storage or control logic.

## Fast Passive Parallel Configuration Timing

This section describes the fast passive parallel (FPP) configuration timing parameters for Stratix V devices.

### DCLK-to-DATA[] Ratio for FPP Configuration

FPP configuration requires a different DCLK-to-DATA [] ratio when you enable the design security, decompression, or both features. Table 49 lists the DCLK-to-DATA [] ratio for each combination.

**Table 49. DCLK-to-DATA[] Ratio <sup>(1)</sup> (Part 1 of 2)**

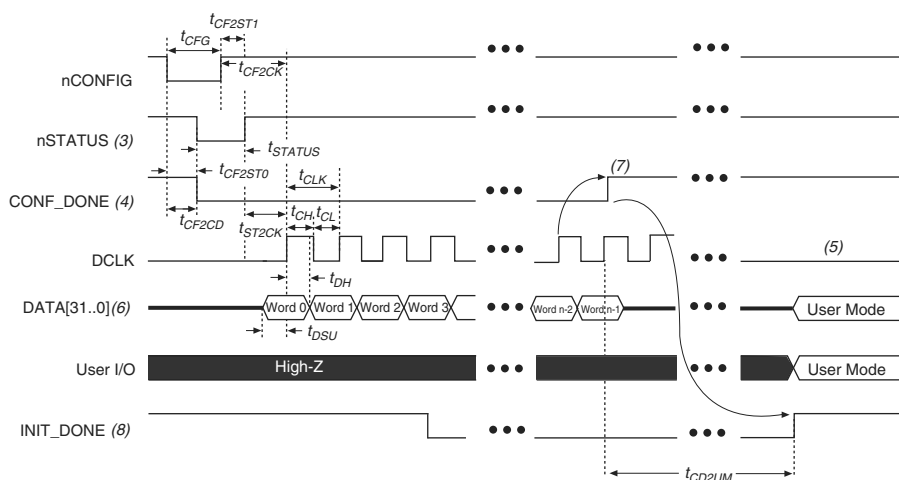
Configuration Scheme	Decompression	Design Security	DCLK-to-DATA[] Ratio
FPP ×8	Disabled	Disabled	1
	Disabled	Enabled	1
	Enabled	Disabled	2
	Enabled	Enabled	2
FPP ×16	Disabled	Disabled	1
	Disabled	Enabled	2
	Enabled	Disabled	4
	Enabled	Enabled	4



## FPP Configuration Timing when DCLK-to-DATA [] = 1

Figure 12 shows the timing waveform for FPP configuration when using a MAX II or MAX V device as an external host. This waveform shows timing when the DCLK-to-DATA [] ratio is 1.

**Figure 12. FPP Configuration Timing Waveform When the DCLK-to-DATA[] Ratio is 1 <sup>(1), (2)</sup>**



### Notes to Figure 12:

- (1) Use this timing waveform when the DCLK-to-DATA [] ratio is 1.
- (2) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF\_DONE are at logic-high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (3) After power-up, the Stratix V device holds nSTATUS low for the time of the POR delay.
- (4) After power-up, before and during configuration, CONF\_DONE is low.
- (5) Do not leave DCLK floating after configuration. DCLK is ignored after configuration is complete. It can toggle high or low if required.
- (6) For FPP x16, use DATA [15..0]. For FPP x8, use DATA [7..0]. DATA [31..0] are available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings.
- (7) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF\_DONE is released high when the Stratix V device receives all the configuration data successfully. After CONF\_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (8) After the option bit to enable the INIT\_DONE pin is configured into the device, the INIT\_DONE goes low.

Table 51 lists the timing parameters for Stratix V devices for FPP configuration when the DCLK-to-DATA [] ratio is more than 1.

**Table 51. FPP Timing Parameters for Stratix V Devices When the DCLK-to-DATA[] Ratio is >1 <sup>(1)</sup>**

Symbol	Parameter	Minimum	Maximum	Units
$t_{CF2CD}$	nCONFIG low to CONF_DONE low	—	600	ns
$t_{CF2ST0}$	nCONFIG low to nSTATUS low	—	600	ns
$t_{CFG}$	nCONFIG low pulse width	2	—	$\mu$ s
$t_{STATUS}$	nSTATUS low pulse width	268	1,506 <sup>(2)</sup>	$\mu$ s
$t_{CF2ST1}$	nCONFIG high to nSTATUS high	—	1,506 <sup>(2)</sup>	$\mu$ s
$t_{CF2CK}$ <sup>(5)</sup>	nCONFIG high to first rising edge on DCLK	1,506	—	$\mu$ s
$t_{ST2CK}$ <sup>(5)</sup>	nSTATUS high to first rising edge of DCLK	2	—	$\mu$ s
$t_{DSU}$	DATA [] setup time before rising edge on DCLK	5.5	—	ns
$t_{DH}$	DATA [] hold time after rising edge on DCLK	$N-1/f_{DCLK}$ <sup>(5)</sup>	—	s
$t_{CH}$	DCLK high time	$0.45 \times 1/f_{MAX}$	—	s
$t_{CL}$	DCLK low time	$0.45 \times 1/f_{MAX}$	—	s
$t_{CLK}$	DCLK period	$1/f_{MAX}$	—	s
$f_{MAX}$	DCLK frequency (FPP $\times 8/\times 16$ )	—	125	MHz
	DCLK frequency (FPP $\times 32$ )	—	100	MHz
$t_R$	Input rise time	—	40	ns
$t_F$	Input fall time	—	40	ns
$t_{CD2UM}$	CONF_DONE high to user mode <sup>(3)</sup>	175	437	$\mu$ s
$t_{CD2CU}$	CONF_DONE high to CLKUSR enabled	$4 \times$ maximum DCLK period	—	—
$t_{CD2UMC}$	CONF_DONE high to user mode with CLKUSR option on	$t_{CD2CU} + (8576 \times \text{CLKUSR period})$ <sup>(4)</sup>	—	—

**Notes to Table 51:**

- (1) Use these timing parameters when you use the decompression and design security features.
- (2) You can obtain this value if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.
- (3) The minimum and maximum numbers apply only if you use the internal oscillator as the clock source for initializing the device.
- (4) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the Initialization section of the “Configuration, Design Security, and Remote System Upgrades in Stratix V Devices” chapter.
- (5) N is the DCLK-to-DATA ratio and  $f_{DCLK}$  is the DCLK frequency the system is operating.
- (6) If nSTATUS is monitored, follow the  $t_{ST2CK}$  specification. If nSTATUS is not monitored, follow the  $t_{CF2CK}$  specification.

**Table 53. AS Timing Parameters for AS ×1 and AS ×4 Configurations in Stratix V Devices <sup>(1), (2)</sup> (Part 2 of 2)**

Symbol	Parameter	Minimum	Maximum	Units
$t_{CD2UM}$	CONF_DONE high to user mode <sup>(3)</sup>	175	437	μs
$t_{CD2CU}$	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	—	—
$t_{CD2UMC}$	CONF_DONE high to user mode with CLKUSR option on	$t_{CD2CU} + (8576 \times \text{CLKUSR period})$	—	—

**Notes to Table 53:**

- (1) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for initializing the device.
- (2)  $t_{CF2CD}$ ,  $t_{CF2ST0}$ ,  $t_{CFG}$ ,  $t_{STATUS}$ , and  $t_{CF2ST1}$  timing parameters are identical to the timing parameters for PS mode listed in Table 54 on page 63.
- (3) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on this pin, refer to the Initialization section of the “Configuration, Design Security, and Remote System Upgrades in Stratix V Devices” chapter.

## Passive Serial Configuration Timing

Figure 15 shows the timing waveform for a passive serial (PS) configuration when using a MAX II device, MAX V device, or microprocessor as an external host.

**Figure 15. PS Configuration Timing Waveform <sup>(1)</sup>****Notes to Figure 15:**

- (1) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF\_DONE are at logic high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (2) After power-up, the Stratix V device holds nSTATUS low for the time of the POR delay.
- (3) After power-up, before and during configuration, CONF\_DONE is low.
- (4) Do not leave DCLK floating after configuration. You can drive it high or low, whichever is more convenient.
- (5) DATA0 is available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings in the **Device and Pins Option**.
- (6) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF\_DONE is released high after the Stratix V device receives all the configuration data successfully. After CONF\_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (7) After the option bit to enable the INIT\_DONE pin is configured into the device, the INIT\_DONE goes low.

**Table 58. IOE Programmable Delay for Stratix V Devices (Part 2 of 2)**

Parameter (1)	Available Settings	Min Offset (2)	Fast Model		Slow Model							
			Industrial	Commercial	C1	C2	C3	C4	I2	I3, I3YY	I4	Unit
D3	8	0	1.587	1.699	2.793	2.793	2.992	3.192	2.811	3.047	3.257	ns
D4	64	0	0.464	0.492	0.838	0.838	0.924	1.011	0.843	0.920	1.006	ns
D5	64	0	0.464	0.493	0.838	0.838	0.924	1.011	0.844	0.921	1.006	ns
D6	32	0	0.229	0.244	0.415	0.415	0.458	0.503	0.418	0.456	0.499	ns

**Notes to Table 58:**

- (1) You can set this value in the Quartus II software by selecting **D1**, **D2**, **D3**, **D5**, and **D6** in the **Assignment Name** column of **Assignment Editor**.
- (2) Minimum offset does not include the intrinsic delay.

## Programmable Output Buffer Delay

Table 59 lists the delay chain settings that control the rising and falling edge delays of the output buffer. The default delay is 0 ps.

**Table 59. Programmable Output Buffer Delay for Stratix V Devices (1)**

Symbol	Parameter	Typical	Unit
D <sub>OUTBUF</sub>	Rising and/or falling edge delay	0 (default)	ps
		25	ps
		50	ps
		75	ps

**Note to Table 59:**

- (1) You can set the programmable output buffer delay in the Quartus II software by setting the **Output Buffer Delay Control** assignment to either positive, negative, or both edges, with the specific values stated here (in ps) for the **Output Buffer Delay** assignment.

## Glossary

Table 60 lists the glossary for this chapter.

**Table 60. Glossary (Part 1 of 4)**

Letter	Subject	Definitions
A	—	—
B		
C		
D	—	—
E	—	—
F	f <sub>HCLK</sub>	Left and right PLL input clock frequency.
	f <sub>HSDR</sub>	High-speed I/O block—Maximum and minimum <b>LVDS</b> data transfer rate (f <sub>HSDR</sub> = 1/TUI), non-DPA.
	f <sub>HSDRDPA</sub>	High-speed I/O block—Maximum and minimum <b>LVDS</b> data transfer rate (f <sub>HSDRDPA</sub> = 1/TUI), DPA.

**Table 61. Document Revision History (Part 3 of 3)**

Date	Version	Changes
May 2013	2.7	<ul style="list-style-type: none"> <li>■ Updated Table 2, Table 6, Table 7, Table 20, Table 23, Table 27, Table 47, Table 60</li> <li>■ Added Table 24, Table 48</li> <li>■ Updated Figure 9, Figure 10, Figure 11, Figure 12</li> </ul>
February 2013	2.6	<ul style="list-style-type: none"> <li>■ Updated Table 7, Table 9, Table 20, Table 23, Table 27, Table 30, Table 31, Table 35, Table 46</li> <li>■ Updated “Maximum Allowed Overshoot and Undershoot Voltage”</li> </ul>
December 2012	2.5	<ul style="list-style-type: none"> <li>■ Updated Table 3, Table 6, Table 7, Table 8, Table 23, Table 24, Table 25, Table 27, Table 30, Table 32, Table 35</li> <li>■ Added Table 33</li> <li>■ Added “Fast Passive Parallel Configuration Timing”</li> <li>■ Added “Active Serial Configuration Timing”</li> <li>■ Added “Passive Serial Configuration Timing”</li> <li>■ Added “Remote System Upgrades”</li> <li>■ Added “User Watchdog Internal Circuitry Timing Specification”</li> <li>■ Added “Initialization”</li> <li>■ Added “Raw Binary File Size”</li> </ul>
June 2012	2.4	<ul style="list-style-type: none"> <li>■ Added Figure 1, Figure 2, and Figure 3.</li> <li>■ Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table 27, Table 29, Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 41, Table 43, Table 56, and Table 59.</li> <li>■ Various edits throughout to fix bugs.</li> <li>■ Changed title of document to <i>Stratix V Device Datasheet</i>.</li> <li>■ Removed document from the Stratix V handbook and made it a separate document.</li> </ul>
February 2012	2.3	<ul style="list-style-type: none"> <li>■ Updated Table 1–22, Table 1–29, Table 1–31, and Table 1–31.</li> </ul>
December 2011	2.2	<ul style="list-style-type: none"> <li>■ Added Table 2–31.</li> <li>■ Updated Table 2–28 and Table 2–34.</li> </ul>
November 2011	2.1	<ul style="list-style-type: none"> <li>■ Added Table 2–2 and Table 2–21 and updated Table 2–5 with information about Stratix V GT devices.</li> <li>■ Updated Table 2–11, Table 2–13, Table 2–20, and Table 2–25.</li> <li>■ Various edits throughout to fix SPRs.</li> </ul>
May 2011	2.0	<ul style="list-style-type: none"> <li>■ Updated Table 2–4, Table 2–18, Table 2–19, Table 2–21, Table 2–22, Table 2–23, and Table 2–24.</li> <li>■ Updated the “DQ Logic Block and Memory Output Clock Jitter Specifications” title.</li> <li>■ Chapter moved to Volume 1.</li> <li>■ Minor text edits.</li> </ul>
December 2010	1.1	<ul style="list-style-type: none"> <li>■ Updated Table 1–2, Table 1–4, Table 1–19, and Table 1–23.</li> <li>■ Converted chapter to the new template.</li> <li>■ Minor text edits.</li> </ul>
July 2010	1.0	Initial release.